CALL FOR PAPERS

ESREF

2026 VIENNA

SEPTEMBER 21-24, 2026

EUROPEAN SYMPOSIUM ON
RELIABILITY OF ELECTRON DEVICES,
FAILURE PHYSICS AND ANALYSIS


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EcoEvent

Environment is VIP in Vienna

ABOUT TU Wien

At the forefront of Austria's academic landscape, **TU Wien** proudly holds the title of the country's largest technology-based and most esteemed academic institution, leading the way in pioneering research and education within the fields of technology and natural sciences. Cultivating a rich legacy spanning over two centuries, **TU Wien** remains steadfast in its commitment to the guiding principle "Technology for People". With more than 4000 dedicated scientists propelling innovation across eight faculties and five key research areas, **TU Wien** stands as the unrivaled hub for technology and sciences in Austria. Semiconductors are a major focus at **TU Wien's Faculty of Electrical Engineering and Information Technology**. With state-of-the-art cleanroom and laboratory facilities, **TU Wien** provides the perfect platform for semiconductor reliability and failure analysis. Founded in 1988, the **Institute for Microelectronics** leads pioneering research in the characterization and modeling of reliability effects, spanning technologies from silicon to power devices such as SiC, GaN, and emerging 2D material. We are honored to host **ESREF 2026**.

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TRACKS / SCOPE OF PAPERS

A: Quality and Reliability Assessment Techniques and Methods for Devices and Systems

B: Reliability for Nanoelectronics

C: Progress in Failure Analysis: Defect Detection and Analysis

D: Reliability of Microwave Devices and Circuits

E: Packaging- and Assembly Reliability and Failure Analysis

F1: Power Devices Reliability: Smart-Power Devices and Silicon Power Devices

F2: Power Devices Reliability: Wide-Bandgap Devices

F3: Power Devices Reliability: Power Electronic Systems

G: Photonics Reliability

H: MEMS and Sensor Reliability

I: Extreme Environments and Radiation

J: Automotive and Industrial Electronic Reliability

PUBLICATION

The Technical Program Committee will invite authors of accepted papers to submit their work to a Special Issue in *Microelectronics Engineering* or in *IEEE Xplore*. More details can be found on the conference website.

AUTHOR INFORMATION

Authors are invited to submit an extended 4-page abstract of their original research contributions to **ESREF 2026**. Submission guidelines and templates are available on the conference website.

IEEE
Austria Section

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ESREF
2026

SOCIAL EVENTS

MONDAY, 21st September 2026:

General Chair's Reception – Kuppelsaal, TU Wien
(Karlsplatz 13, 1040 Vienna)

TUESDAY, 22nd September 2026:

Poster Session – Conference Venue
(Gusshausstrasse 27-29, 1040 Vienna)

WEDNESDAY, 23rd September 2026:

Gala Dinner – Vienna City Hall
(Friedrich-Schmidt-Platz 1, 1010 Vienna)

More information on the **technical and social program** will be provided on the conference website, on LinkedIn, and via email updates.

CONFERENCE VENUE

TU Wien / Institute for Microelectronics
Campus Gusshaus
Gusshausstrasse 27-29, 1040 Vienna, Austria

ORGANIZATION COMMITTEE

GENERAL CHAIR	**Michael Waltl** waltl@iue.tuwien.ac.at Tel: + 43 1 58801 - 36050
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AUTHORS:

20.03.2026	**Abstract Submission Deadline**
12.05.2026	**Notification of Acceptance**
	Invitation to submit a paper to Microelectronics Engineering (Instructions will be sent to authors by e-mail)
after ESREF	**Publication of Journal Papers and Conference Proceedings**

ATTENDEES:

01.05.2026	**Start of Conference Registration**
31.07.2026	**End of Early Bird Registration**
11.09.2026	**Final Deadline for Online Registration**

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Issue: December 2025